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Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2010 [Approved on 19 July 2024, 13:21 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.4%	Nickel REACH Article 67 Exemption	7440-02-0	0.95%
			Gold	7440-57-5	10.95%
			Polydimethylsiloxane rubber	63394-02-5	25.2%
			Silicon	7440-21-3	62.9%
Die attach	Lead and Lead alloys	0.2%	Silver	7440-22-4	1.5%
			Tin	7440-31-5	5.297%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	93.203%
Encapsulation	EP (Epoxy resin)	44.9%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			Tetrabromobisphenol A (TBBPA) Exempt from other regulatory requirements	79-94-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Leadfinish	Tin plating	2.2%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	52.3%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-201	DO-201	0.8	g